



SAMPLE RETURN

TEST REPORT

REPORT NO.KA/2004/50284
DATE: 2004/5/24
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THE FOLLOWING MERCHANDISE WAS(WERE) SUBMITTED AND IDENTIFIED BY THE CLIENT AS :

CLIENT : ADVANCED SEMICONDUCTOR ENGINEERING INC..
PRODUCT DESCRIPTION : IC COMPONENT PACKAGE.
PACKAGE TYPE : QFP 28X28 (GREEN/ROHS COMPLIANCE).
BOM : COMPOUND:SUMITOMO G700A.
EPOXY : ABLESTIK 2288A.
LEAD FRAME : OLIN C7025(Cu)/A42.
LEAD FINISH : MATT Sn.
INK : INK/LASER.
GOLD WIRE : 99.99% Au.
DIE : SILICONE.
TESTING DATE : 2004/5/18 TO 2004/5/24 .
SAMPLE RECEIVED : 2004/05/17.

WE HAVE TESTED THE SAMPLE(S) SUBMITTED AS REQUESTED AND THE FOLLOWING RESULTS WERE OBTAINED.

TEST ITEM(S)	UNIT	METHOD	DET. LMT	RESULT
CADMIUM	ppm	ANALYSIS BY ICP-AES WITH ADVANCE TREATMENT EN1122, METHOD B:2001.	2	n.d.
CHROMIUM VI	ppm	ANALYSIS BY US EPA 7196A WITH ADVANCE TREATMENT US EPA 3060A.	2	n.d.
MERCURY	ppm	ANALYSIS BY ICP-AES WITH ADVANCE TREATMENT US EPA 3052	2	n.d.
LEAD	ppm	ANALYSIS BY ICP-AES WITH ADVANCE TREATMENT US EPA 3050B	2	n.d.
PBBs	%	WITH REFERENCE TO 83/264/EEC. ANALYSIS WAS PERFORMED BY GC/ECDMS OR HPLC/DAD/MS.	0.0005	n.d.
PBDEs	%	WITH REFERENCE TO 83/264/EEC. ANALYSIS WAS PERFORMED BY GC/ECDMS OR HPLC/DAD/MS.	0.0005	n.d.

NOTE : n.d. = not detected.

<END>



George Huang / Supervisor
Sign for and on behalf of
SGS Taiwan Limited

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